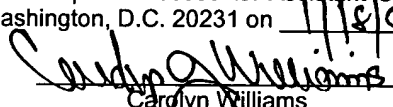
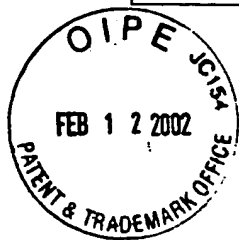


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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE	
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> FEB 19 2002	<b>Atty. Docket No. (Opt.)</b> <b>XDEV1100</b>
Applicant <b>Martin E. Kordesch et al.</b>	
Application Number <b>09/682,151</b>	Filed <b>July 27, 2001</b>
For <b>Contact Method for Thin Silicon Carbide Epitaxial Layer and Semiconductor Devices Formed by Those Methods</b>	
Group Art Unit <b>2811</b>	Examiner <b>Unknown</b>
<b>Certification Under 37 C.F.R. §1.8</b> I hereby certify that the documents listed below are being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on <u>1/18/02</u> , 2002.  Carolyn Williams	



Assistant Commissioner for Patents  
Washington, D.C. 20231

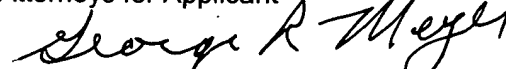
Applicants respectfully request, pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, that the art listed on the attached PTO-1449 form be considered and cited in the examination of the above-identified application. A copy of the art is enclosed for the convenience of the Examiner. Furthermore, pursuant to 37 C.F.R. §§ 1.97(g) and (h), no representation is made that a search has been made or that this art is material to patentability of the present application.

While Applicants believe no fees are due, if any fees are due, the Commissioner is hereby authorized to charge Deposit Account No. 50-0456 of Gray Cary Ware & Freidenrich LLP.

Applicants respectfully submit that the claims of Applicants' above-referenced patent application are patentably distinguishable from these references.

Respectfully submitted,

**Gray Cary Ware & Freidenrich LLP**  
Attorneys for Applicant

  
George R. Meyer  
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Date: 1/18/2002, 2002

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*I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as FIRST CLASS MAIL in an envelope addressed to: Assistant Commissioner for Patents; Washington, DC 20231.*

1/18/02  
Date

Candace Williams  
Signature